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CLAIMS

1. A semiconductor package comprising:

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a semiconductor device with one or more device-side electrodes being formed on a circuit-bearing surface; and

a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed on either or both sides of the patterned wiring, the flexible substrate being bent around said semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side surface of said flexible substrate, the first electrode being connected to said device-side electrode of said semiconductor device and sealed by said thermoplastic insulating layer, and a second electrode provided on a surface different from the surface on which said first electrode is provided; and

said flexible substrate has at least two or more layers of patterned wiring formed thereon.

- 2. The semiconductor package according to claim 1, wherein said flexible substrate has a groove or a portion having less number of wiring layers formed at a bend of said flexible substrate or on a region including the bent.
- 3. The semiconductor package according to claim 2, wherein said flexible substrate has a cavity formed on said

 25 flexible substrate so as to accommodate said semiconductor device in said cavity portion.
 - 4. The semiconductor package according to claim 2, wherein said flexible substrate includes portions where the

flexible substrate is bent and which are directly adhered to each other.

- 5. The semiconductor package according to claim 1, wherein said flexible substrate has a cavity formed on said flexible substrate so as to accommodate said semiconductor device in said cavity portion.
 - 6. A semiconductor package comprising:

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a semiconductor device with one or more device-side electrodes being formed on a circuit-bearing surface; and

a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed on either or both sides of the patterned wiring, said flexible substrate being bent around said semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side surface of the flexible substrate, said first electrode being connected to the device-side electrode of said semiconductor device and sealed by said thermoplastic insulating layer, and a second electrode provided on a surface different from the surface on which said first electrode is provided; and

said flexible substrate includes portions where the flexible substrate is bent and which are directly adhered to each other.

- 7. The semiconductor package according to claim 6, wherein the semiconductor device is accommodated in a recessed portion created by said flexible substrate being bent and directly adhered to each other.
 - 8. A stacked semiconductor package wherein

a plurality of semiconductor packages of the same type or different types according to any one of claims 1 to 7 are electrically connected via said electrodes and three-dimensionally stacked in layers.

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